

Abstract**Method for producing semiconductor wafers by means of a wire saw, wire saw
and semiconductor wafer of monocrystalline silicon**

5

Method for producing semiconductor wafers from a workpiece by processing the workpiece by means of a wire saw, wire saw and semiconductor wafer of monocrystalline silicon. The method comprises

- 10 feeding the workpiece through an arrangement of wires which are tensioned between wire guide rollers while being divided into wire groups and move in a running direction; producing kerfs when the wires engage into the workpiece;
for each of the wire groups, determining a placement error of the kerfs of the wire group; and
- 15 for each of the wire groups, inducing compensating movements of the wires of the wire group as a function of the determined placement error of the kerfs of the wire group in a direction perpendicular to the running direction of the wires of the wire group during the feeding of the workpiece through the arrangement of wires by activating at least one drive element.

20

Drawing for the abstract: Fig. 2